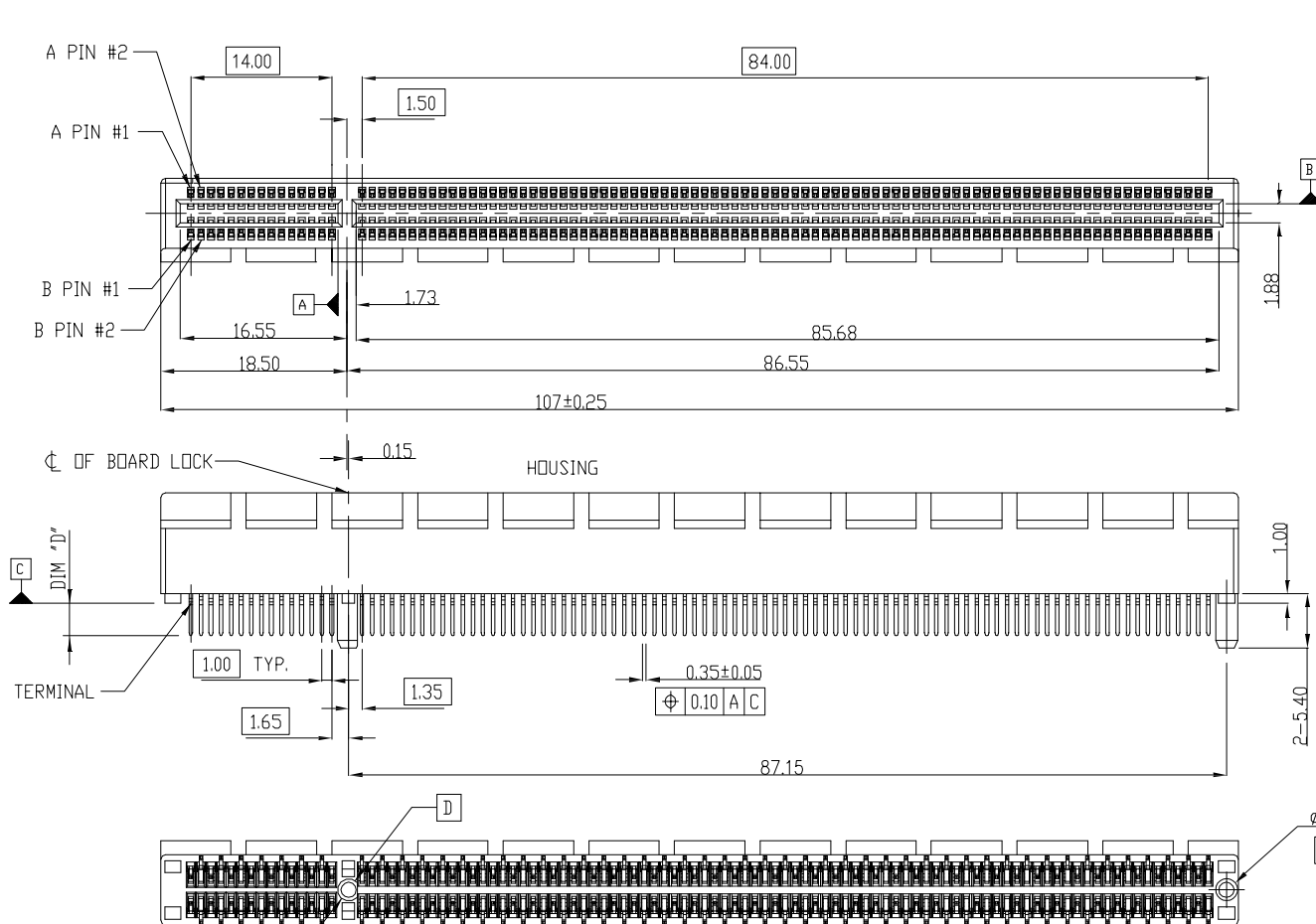
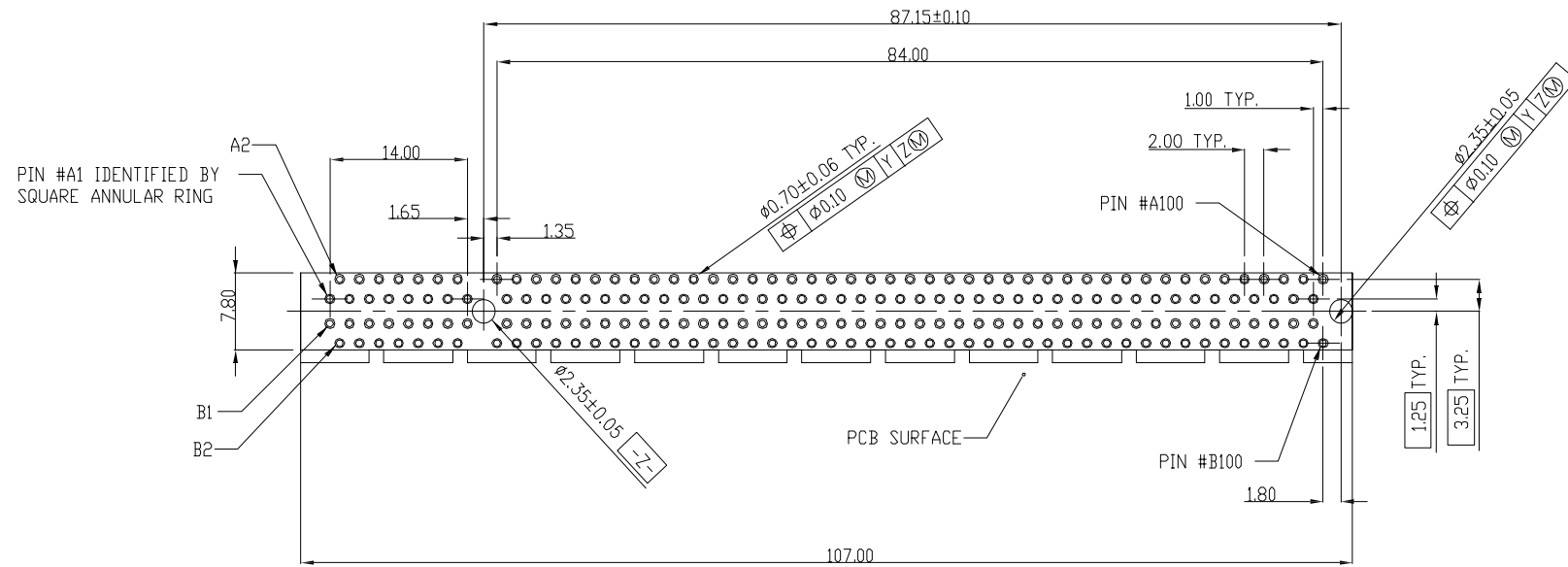


PROD NO
SEE NOTE



mat'l. code				tolerances unless otherwise specified				CUSTOMER COPY		A FCI www.fciconnect.com							
ltr	ecn no	dr	date	linear	.X ±.38				projection 	title PCI-E 200P CARD EDGE GEN3 							
A	T06-0079	J.H	4/14/06		.XX ±.25												
B	ELX-DG-21161-1	S T	05/27/15		.XXX ±.10												
				angles	0° ±2°				MM ↔	product family				PCI		code	
				dr	STONE LI	05/27/15		size				dwg no		—			
				engr	STONE LI	05/27/15											
				chr	/	/								sheet			
				appd	PM ZHENG	05/27/15		N/A				A4				1 of 4	
sheet index	revision sheet	B	B	B	B												
		1	2	3	4												



MOTHER BOARD FOOTPRINT PATTERN
CONECTOR SIDE SHOWN

mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY		A FCI www.fciconnect.com	
ltr	ecn no	dr	date	linear	.X ±.38		projection 	title PCI-E 200P CARD EDGE GEN3 		
					.XX ±.25					
					.XXX ±.10					
				angles	0° ±2°		MM 	product family PCI size dwg no A4 10054652		
			dr	STONE LI	05/27/15					
			enrg	STONE LI	05/27/15					
				chr	/	/	scale N/A	sheet 2 of 4		
			appd	PM ZHENG	05/27/15					
sheet index	revision sheet									

cage code
22526

NOTES:

1.MATERIAL:

HOUSING: THERMOPLASTIC WITH GLASS FIBER, UL94V-0,
COLOR IN BLACK.
CONTACTS: COPPER ALLOY.

2.FINISH:

CONTACTS: GOLD PLATING ON CONTACT AREA,
100 μ MIN. TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDER TAILS,
50 μ MIN. NICKEL UNDERPLATING OVER ALL.
BOARDLOCKS: 100 μ TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDER TAILS,
50 μ MIN. NICKEL UNDERPLATING OVER ALL.

3. DURABILITY: 50 CYCLES.

4. RoHS COMPATIBLE PRODUCT SPECIFICATIONS

- a. PLATING: "LF" MEANS THE PRODUCT IS LEAD FREE, 2.5um min. MATTE PURE TIN OVER 1.27um MIN.
NICKEL UNDERPLATE.
- b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 260C $\pm$ 5C $\circ$
SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH
A 1.60MM THICK CIRCUIT BOARD.

PRODUCT NUMBER CODE

10054652 - X X X X X X LF

HOUSING COLOR OPTIONS
1-BLACK

PEGS OPTIONS
0-PLASTIC PEGS

TERMINAL PLATING OPTIONS
0-50 μ Ni UNDERPLATE
30 μ Au CONTACT AREA
100 μ TIN TAIL AREA -----COMPATIBLE RoHS
1-50 μ Ni UNDERPLATE
15 μ Au CONTACT AREA
100 μ TIN TAIL AREA -----COMPATIBLE RoHS
2-50 μ Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100 μ TIN TAIL AREA -----COMPATIBLE RoHS

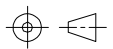
LEAD FREE

PACKAGING OPTIONS
T-TRAY PACKAGING

RESERVE
0

TAIL LENGTH OPTIONS

	DIM "D"	SUGGESTED PCB THICKNESS
1	3.10	2.36 $\pm$ 0.10
2	2.54	1.56 $\pm$ 0.10

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	 www.fciconnect.com
ltr	ecn no	dr	date	linear	.X $\pm$.38		
					.XX $\pm$.25		
					.XXX $\pm$.10		
				angles	0 $\circ$ $\pm$ 2 $\circ$	 MM scale N/A	title PCI-E 200P CARD EDGE GEN3 
				dr	STONE LI 05/27/15		
				enrg	STONE LI 05/27/15		
				chr	/ /		
				appd	PM ZHENG 05/27/15	product family PCI size A4 10054652	code — sheet 4 of 4
sheet	revision						
index	sheet						

cage code
22526